

February 3, 2026

Company name: IBIDEN CO., LTD.

Representative: Koji Kawashima, President & CEO, Representative Director

Stock exchange listings: Tokyo and Nagoya Stock Exchange (Code number: 4062)

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Notice Regarding Capital Investment for High-Performance IC Package Substrates **(Acquisition of Fixed Assets)**

IBIDEN CO., LTD. (hereinafter “the Company”) hereby announces that the Board of Directors, at a meeting held today, resolved to approve a capital investment plan for its electronics business, amounting to approximately 500 billion yen over the three-year period from fiscal year 2026 to fiscal year 2028, with the aim of achieving the fiscal year 2030 targets disclosed in May last year. As the first phase of this plan, the Company hereby announces our resolution to implement additional capital investment, primarily for the existing Gama Plant (Cell6), for the purpose of expanding the production capacity of high-performance IC package substrates, mainly for high-performance servers.

1. Overview of the Capital Investment Plan

1. Purpose : Expansion of Production Capacity for High-Performance IC Package Substrates (for AI Servers and High-performance Servers)
2. Planned Period : Fiscal Year 2026 to Fiscal Year 2028 (three-year period)
3. Total Investment : Approximately 500 billion yen
4. Target : 1. Gama Plant (3-200 Gama-cho, Ogaki City, Gifu Prefecture) and other existing plants, including those overseas
2. Ono Plant (237-1 Shimoiso, Ono-cho, Ibi-gun, Gifu Prefecture) and other existing plants, including those overseas
5. Details of the Capital Investment Plan:
 - <Place> Gama Plant and other existing plants, including those overseas
 - <Investment Amount> Approximately 220 billion yen (planned)
 - <Operation Start> Sequential operation and planned commencement of mass production from fiscal year 2027
 - <Production Capacity> Through this investment, the Company will increase production capacity to meet the demand for high-performance IC package substrates from fiscal year 2027 onwards

2. Future Outlook

The impact of this investment on the Company's consolidated financial results for the current fiscal year is expected to be immaterial.

End